

1.0A Avg.

30 Volts

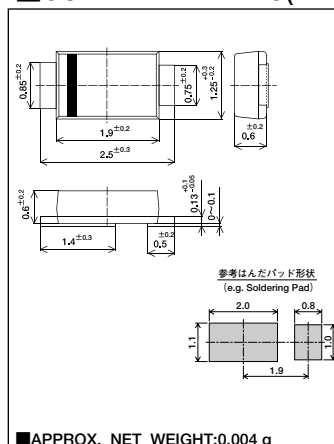
SBD

SA10QA03

最大定格 Maximum Ratings

Item	Symbol	Conditions	Unit
くり返しピーク逆電圧 Repetitive Peak Reverse Voltage	V_{RRM}	30	V
直流順電流 Direct Forward Current	I_{DC}	直流通電 Direct Current $T_a=86^{\circ}\text{C}^{*1}$	1.41 A
平均整流電流 Average rectified Forward Current	I_o	方形波通電 RECT 180 $^{\circ}$ Rectangular Wave 50% Duty $T_a=73^{\circ}\text{C}^{*1}, V_{RM}=15\text{V}$ $T_l=124^{\circ}\text{C}, V_{RM}=15\text{V}$ (T_l : Lead Temperature)	1.0 A
サージ順電流 Surge Forward Current	I_{FSM}	20 (50Hz正弦半波1サイクル非くり返し) Half Sine Wave, 1cycle, Non-repetitive	A
動作接合温度範囲 Operating Junction Temperature Range	T_{jw}	-40~+150	$^{\circ}\text{C}$
保存温度範囲 Storage Temperature Range	T_{stg}	-40~+150	$^{\circ}\text{C}$

OUTLINE DRAWING(mm)



APPROX. NET WEIGHT:0.004 g

電氣的・熱的特性 Electrical/Thermal Characteristics

Item	Symbol	Conditions	Min.	Typ.	Max.	Unit
ピーク逆電流 Peak Reverse Current	I_{RM}	$V_{RM}=5\text{V}$ $T_a=25^{\circ}\text{C}$	—	1	—	μA
ピーク順電圧 Peak Forward Voltage	V_{FM}	$V_{RM}=30\text{V}$ $T_a=25^{\circ}\text{C}$ $I_{FM}=0.7\text{A}$ $T_a=25^{\circ}\text{C}$ $I_{FM}=1.0\text{A}$ $T_a=25^{\circ}\text{C}$	—	10 0.42 0.47	100 0.45 —	mA V
熱抵抗 Thermal Resistance	$R_{th(j-a)}$	接合部・周囲間 (Junction to Ambient) *1 (アルミナ基板実装) *2 (ガラスエポキシ基板実装)	—	—	100 150	$^{\circ}\text{C/W}$
	$R_{th(j-l)}$	接合部・リード間 (Junction to Lead)	—	—	30	

*1: プリント基板実装/Alumina Substrate Mounted (Soldering Land=6×6mm)

*2: プリント基板実装/Glass-Epoxy Substrate Mounted (Soldering Land=6×6mm)

定格・特性曲線

FIG.1
順電圧特性
FORWARD CURRENT VS. VOLTAGE

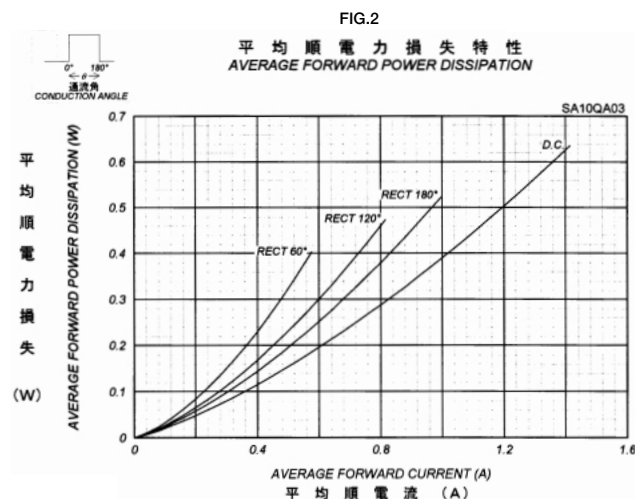
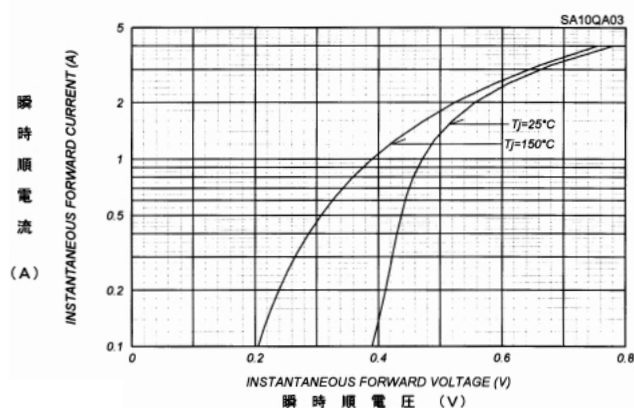


FIG.3
ピーク逆電流 - ピーク逆電圧特性
PEAK REVERSE CURRENT VS. PEAK REVERSE VOLTAGE
 $T_j=150^{\circ}\text{C}$

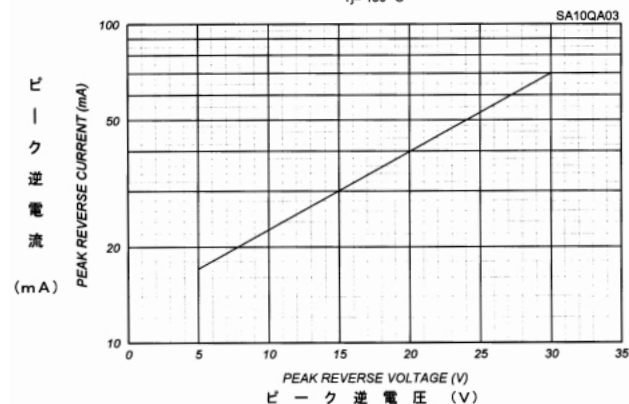
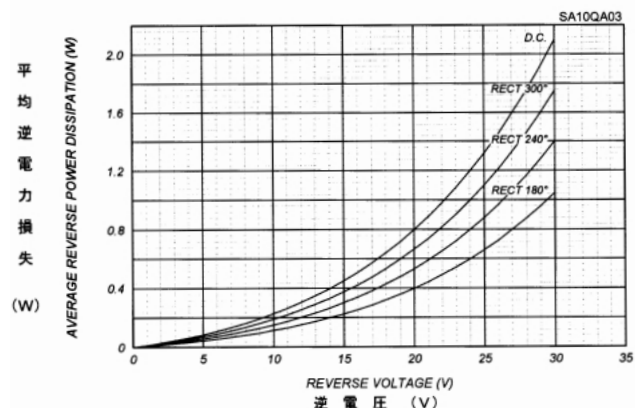


FIG.4
平均逆電力損失
AVERAGE REVERSE POWER DISSIPATION



1.0A Avg.

30 Volts

SBD

SA10QA03

FIG.5

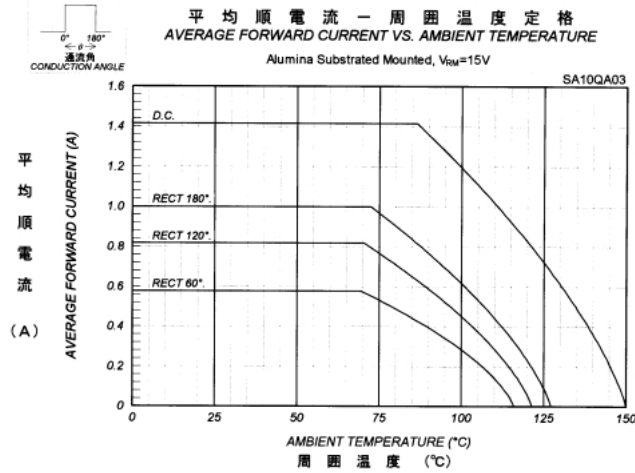


FIG.6

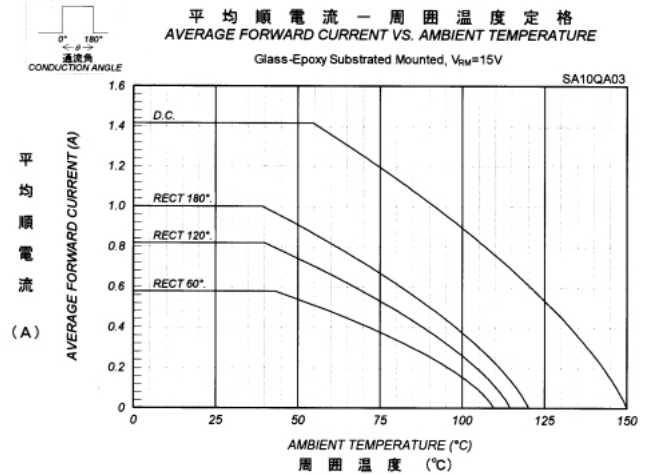


FIG.7

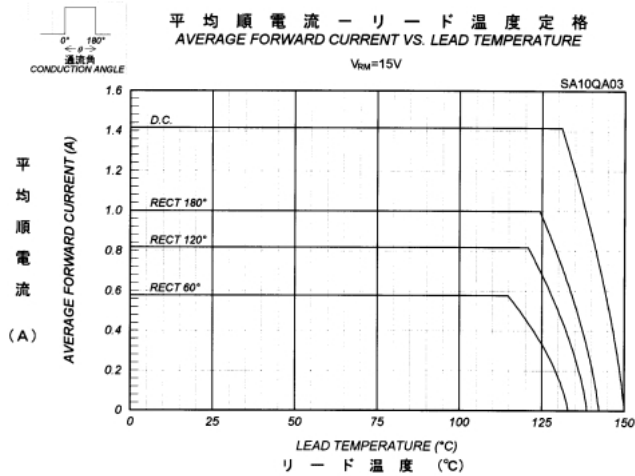


FIG.8

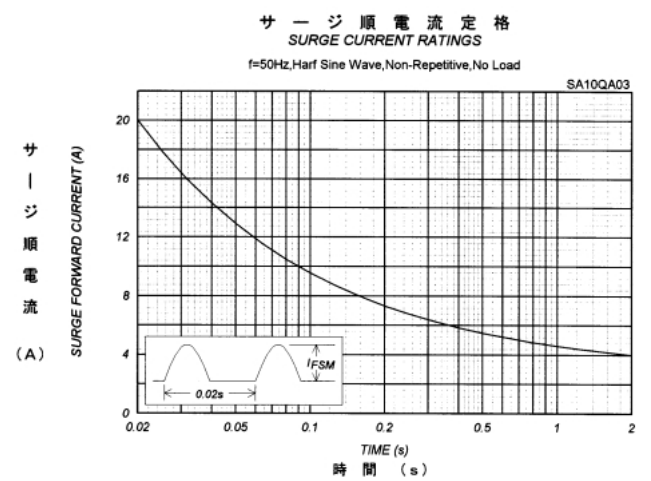


FIG.9

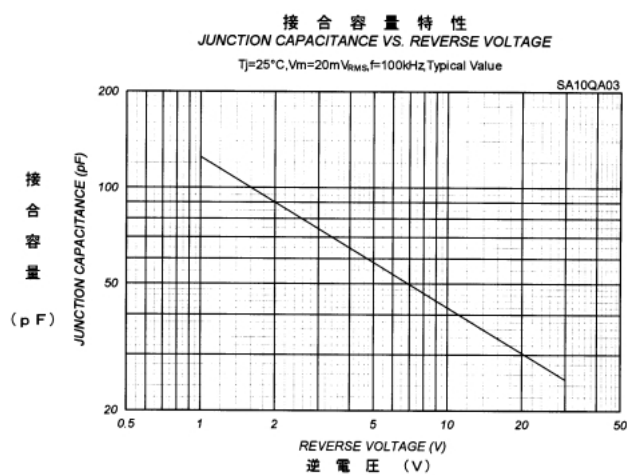


FIG.10

